AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Previously Presented) A method of producing synthetic resin film for laminates, said synthetic resin film comprising a substrate impregnated with a thermosetting resin, said method comprising

(a) impregnating the substrate with a first thermosetting resin composition comprising a first uncured thermosetting resin and a low profile additive,

(b) drying the impregnated substrate of (a),

(c) impregnating the substrate of (b) with a second thermosetting resin composition comprising a second uncured thermosetting resin and a low profile additive, and

(d) drying the impregnated substrate of (c).

2. (Previously Presented) The method of claim 39, further comprising at least partially curing the first uncured thermosetting resin in the impregnated substrate.

3. (Previously Presented) The method of claim 39, wherein said low profile additive comprises ceramic microspheres.

4. (Previously Presented) The method of claim 39, wherein said low profile additive comprises thermoplastic polymer powder.

5. (Previously Presented) The method of claim 39, wherein said low profile additive comprises polyethylene powder.

6. (Previously Presented) The method of claim 39, wherein said first and second uncured thermosetting resin are each selected from the group consisting of melamine-formaldehyde, urea-formaldehyde, phenol-formaldehyde and mixtures thereof.

7. (Previously Presented) The method of claim 39, wherein the substrate is paper.

8. (Previously Presented) The method of claim 39, wherein the low profile additive is present in amounts sufficient to provide said synthetic resin film with a scratch resistance of about 2.5 Newtons or higher.

9. (Original) Synthetic resin film for laminates produced by the method according to claim 1.

10. (Cancelled)

11. (Previously Presented) The method of claim 1, further comprising at least partially curing the second uncured thermosetting resin in the impregnated substrate.

12. (Previously Presented) The method of claim 1, wherein said first uncured thermosetting resin and said second uncured thermosetting resin are the same.

13-15. (Cancelled)

16. (Previously Presented) The method of claim 1, wherein said first uncured thermosetting resin and said second uncured thermosetting resin are independently selected from the group consisting of melamine-formaldehyde, urea-formaldehyde, phenol formaldehyde and mixtures thereof.

17-25. (Cancelled).

26. (Currently Amended) Synthetic resin film for laminates comprising a substrate impregnated with an at least partially cured thermosetting resin and uncoated ceramic microspheres, wherein the uncoated ceramic microspheres are present in amounts sufficient to provide said synthetic resin film with a scratch resistance of about 2.5 Newtons or higher.

27. (Previously Presented) A process of producing laminate, said process comprising assembling a plurality of layers of synthetic resin film at least one of said layers being the synthetic resin film of claim 9, and subjecting said assembly to heat and pressure sufficient to effect consolidation of said layers to produce a laminate.

28. (Previously Presented) The process of claim 27, wherein the heat necessary to effect consolidation is 230 to 340 degrees F and the pressure necessary to effect consolidation is 800 to 1600 psi.

29. (Previously Presented) The laminate produced by the process of claim 27.

30-32. (Cancelled).

33. (Previously Presented) A laminate comprising a synthetic resin film of claim 9 laminated to a base material.

34. (Previously Presented) The laminate of claim 33, wherein said base material comprises wood.

35. (Previously Presented) The laminate of claim 33, wherein said base material is selected from the group consisting of particle board, medium density fiber board and composite panel.

36 - 38. (Cancelled).

39. (Previously Presented) The method of claim 1, wherein the low profile additive is inert, substantially spherical and has a particle size in the range of about 5 to about 60 microns.

40-44. (Cancelled).

45. (Currently Amended) A method of producing synthetic resin film for laminates, said synthetic resin film comprising a substrate impregnated with a thermosetting resin, said method comprising

(a) impregnating the substrate with a thermosetting resin composition comprising an uncured thermosetting resin and uncoated ceramic microspheres; and

(b) drying the impregnated substrate of (a),

wherein the uncoated ceramic microspheres are present in amounts sufficient to provide said synthetic resin film with a scratch resistance of about 2.5 Newtons or higher.

46. (Previously Presented) The method of claim 45, further comprising

(c) impregnating the substrate of (b) with a second thermosetting resin composition comprising a second uncured thermosetting resin and a low profile additive, and

(d) drying the impregnated substrate of (c).

47. (Cancelled).

48. (Currently Amended) A method of producing synthetic resin film for laminates, said synthetic resin film comprising a substrate impregnated with a thermosetting resin, said method comprising

(a) impregnating the substrate with a thermosetting resin composition comprising an uncured thermosetting resin and uncoated ceramic microspheres; and

(b) drying the impregnated substrate of (a), the uncoated ceramic microspheres comprising about 0.5 to about 4.75% (wt) of the thermosetting resin after drying the impregnated substrate.

49. (Previously Presented) The method of claim 48, further comprising at least partially curing the uncured thermosetting resin in the impregnated substrate.

50. (Previously Presented) The method of claim 48, wherein said uncured thermosetting resin is selected from the group consisting of melamine-formaldehyde, urea-formaldehyde, phenol-formaldehyde and mixtures thereof.

51. (Previously Presented) The method of claim 48, wherein the substrate is paper.

52. (Previously Presented) The method of claim 48, wherein the ceramic microspheres are present in amounts sufficient to provide said synthetic resin film with a scratch resistance of about 2.5 Newtons or higher.

53. (Previously Presented) The method of claim 48, further comprising
(c) impregnating the substrate of (b) with a second thermosetting resin composition comprising a second uncured thermosetting resin and a low profile additive, and
(d) drying the impregnated substrate of (c).

54. (Previously Presented) Synthetic resin film for laminates produced by the method according to claim 48.

55. (Currently Amended) A method of producing synthetic resin film for laminates, said synthetic resin film comprising a substrate impregnated with a thermosetting resin, said method comprising

(a) impregnating the substrate with a thermosetting resin composition comprising an uncured thermosetting resin and uncoated ~~alkali alumino silicate~~ ceramic microspheres; and

(b) drying the impregnated substrate of (a).

56. (Previously Presented) The method of claim 55, further comprising at least partially curing the uncured thermosetting resin in the impregnated substrate.

57. (Previously Presented) The method of claim 55, wherein said uncured thermosetting resin is selected from the group consisting of melamine-formaldehyde, urea-formaldehyde, phenol-formaldehyde and mixtures thereof.

58. (Previously Presented) The method of claim 55, wherein the substrate is paper.

59. (Currently Amended) The method of claim 55, wherein the ~~alkali alumino silicate~~ ceramic microspheres are present in amounts sufficient to provide said synthetic resin film with a scratch resistance of about 2.5 Newtons or higher.

60. (Previously Presented) The method of claim 55, further comprising (c) impregnating the substrate of (b) with a second thermosetting resin composition comprising a second uncured thermosetting resin and a low profile additive, and (d) drying the impregnated substrate of (c).

61. (Previously Presented) Synthetic resin film for laminates produced by the method according to claim 55.

62. (New) The method of claim 55 wherein the ceramic microspheres are alkali alumino silicate ceramic microspheres.